

Certificate of Analysis (CoA)

Aug. 29, 2025

Product Name: Tin Sputtering Target

Chemical Formula: Sn

Purity: 99.9% (3N)

Dimensions: Ø76.2 mm × 3.0 mm (±0.1 mm)

Backing Plate: Elastomer bonded to OFHC Copper plate, 2 mm thick

Quantity: 2 pcs

Lot Number: CSXK-25SC-0830TB

Manufactured by: Thin-Film Materials

Physical Description

- Form: Metallic sputtering target
- Appearance: Silvery-white, soft metallic surface
- Crystal Structure: Tetragonal (β -Sn, room temperature)
- Theoretical Density: ~7.31 g/cm³
- Fabrication: Vacuum cast, machined, elastomer bonded to copper plate

Theoretical Composition

- **Element:** Tin (Sn)
- **Atomic Weight:** 118.71 g/mol
- **Mass Fraction:** 100% Sn (elemental metal)

Chemical Composition (by ICP-OES / GDMS)

Element	Symbol	Max. Content (ppm)
Tin	Sn	Balance (>99.9%)
Lead	Pb	<50
Iron	Fe	<30
Copper	Cu	<30

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Element	Symbol	Max. Content (ppm)
Silicon	Si	<20
Other metals (each) –		<20
Total Impurities	–	<1000 ppm

Handling & Storage

- Tin is soft and easily scratched; handle with care.
 - Store in sealed packaging under vacuum or inert atmosphere.
 - Avoid contamination from dust or fingerprints by using gloves.
 - Keep in a cool, dry environment.
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Declaration

We certify that the above product has been manufactured and tested in accordance with our quality control system and meets the specifications stated herein.

Authorized Signature:Inspection Certificate by: Nancy LiuApprover by: Chen Qiang